



STL35NF10

N-CHANNEL 100V - 0.025Ω - 35A PowerFLAT™ LOW GATE CHARGE STripFET™ MOSFET

PRELIMINARY DATA

TYPE	V _{DSS}	R _{DS(on)}	I _D
STL35NF10	100 V	< 0.030 Ω	35 A

- TYPICAL R_{DS(on)} = 0.025Ω
- IMPROVED DIE-TO-FOOTPRINT RATIO
- VERY LOW PROFILE PACKAGE

DESCRIPTION

This Power MOSFET is the second generation of STMicroelectronics unique "STripFET™" technology. The resulting transistor shows extremely low on-resistance and minimal gate charge. The new PowerFLAT™ package allows a significant reduction in board space without compromising performance.

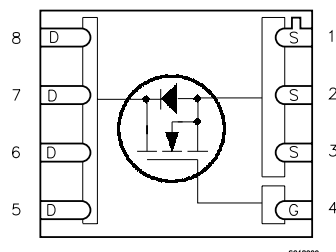
APPLICATIONS

- HIGH EFFICIENCY ISOLATED DC/DC CONVERTERS



**PowerFLAT™ (6x5)
(Chip Scale Package)**

INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	100	V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	100	V
V _{GS}	Gate- source Voltage	± 20	V
I _D	Drain Current (continuos) at T _C = 25°C Drain Current (continuos) at T _C = 100°C	35 22	A A
I _{DM} (●)	Drain Current (pulsed)	140	A
P _{TOT}	Total Dissipation at T _C = 25°C	80	W
	Derating Factor	0.64	W/°C
E _{AS} (1)	Single Pulse Avalanche Energy	135	mJ
T _{stg}	Storage Temperature	-65 to 150	°C
T _j	Max. Operating Junction Temperature	-55 to 150	°C

(●) Pulse width limited by safe operating area

(1) Starting T_j = 25°C, I_D = 35A, V_{DD} = 50V

THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	1.56	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	50	°C/W

ELECTRICAL CHARACTERISTICS (TCASE = 25 °C UNLESS OTHERWISE SPECIFIED)**OFF**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \mu A$, $V_{GS} = 0$	100			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}$, $T_C = 125 \text{ }^\circ\text{C}$			1 10	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20V$			± 100	nA

ON (1)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	2.8	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10 V$, $I_D = 17.5 A$		0.025	0.030	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs} (1)$	Forward Transconductance	$V_{DS} = 20 V$, $I_D = 15 A$		18		S
C_{iss}	Input Capacitance	$V_{DS} = 25 V$, $f = 1 \text{ MHz}$, $V_{GS} = 0$		1780		pF
C_{oss}	Output Capacitance			265		pF
C_{rss}	Reverse Transfer Capacitance			162		pF

ELECTRICAL CHARACTERISTICS (CONTINUED)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 50\text{ V}$, $I_D = 17.5\text{ A}$		28		ns
t_r	Rise Time	$R_G = 4.7\Omega$, $V_{GS} = 10\text{ V}$ (see test circuit, Figure 1)		63		ns
Q_g	Total Gate Charge	$V_{DD} = 80\text{ V}$, $I_D = 35\text{ A}$,		60	80	nC
Q_{gs}	Gate-Source Charge	$V_{GS} = 10\text{ V}$		10		nC
Q_{gd}	Gate-Drain Charge	(see test circuit, Figure 2)		23		nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off-Delay Time	$V_{DD} = 50\text{ V}$, $I_D = 17.5\text{ A}$,		84		ns
t_f	Fall Time	$R_G = 4.7\Omega$, $V_{GS} = 10\text{ V}$ (see test circuit, Figure 1)		28		ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				35	A
$I_{SDM} (1)$	Source-drain Current (pulsed)				140	A
$V_{SD} (2)$	Forward On Voltage	$I_{SD} = 18\text{ A}$, $V_{GS} = 0$			1.2	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 35\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$,		114		ns
Q_{rr}	Reverse Recovery Charge	$V_{DD} = 25\text{ V}$, $T_j = 150^\circ\text{C}$		456		nC
I_{RRM}	Reverse Recovery Current	(see test circuit, Figure 3)		8		A

Note: 1. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.
2. Pulse width limited by safe operating area.

Fig. 1: Switching Times Test Circuit For Resistive Load

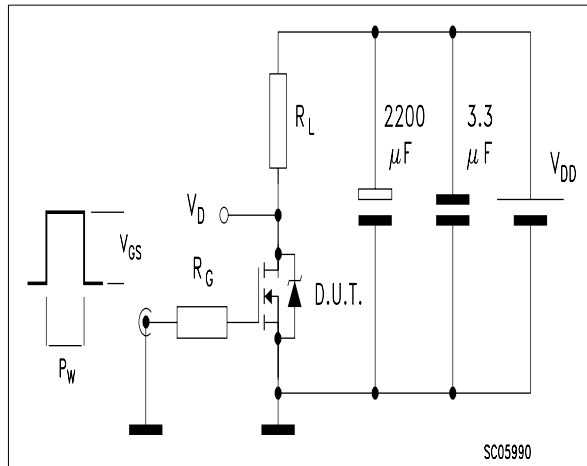


Fig. 2: Gate Charge test Circuit

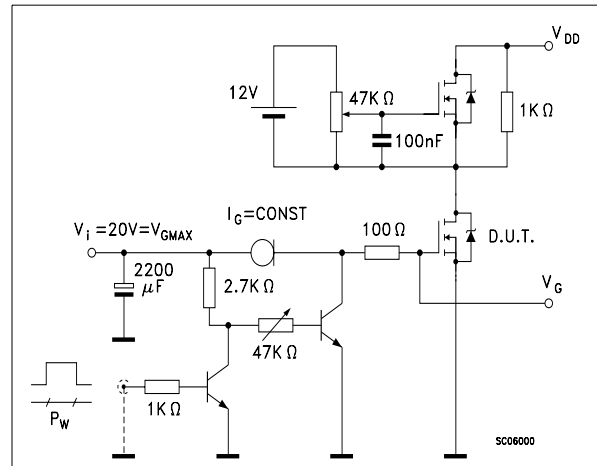
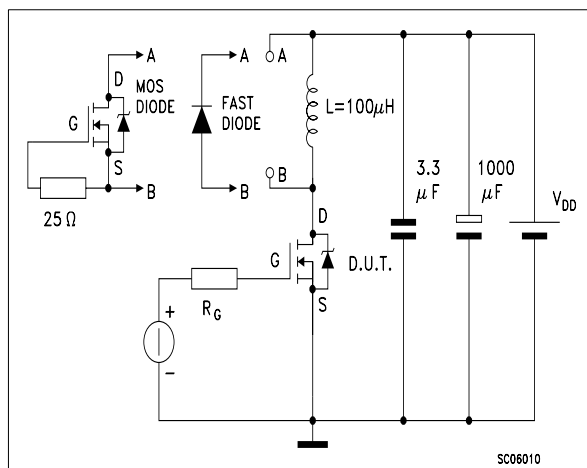
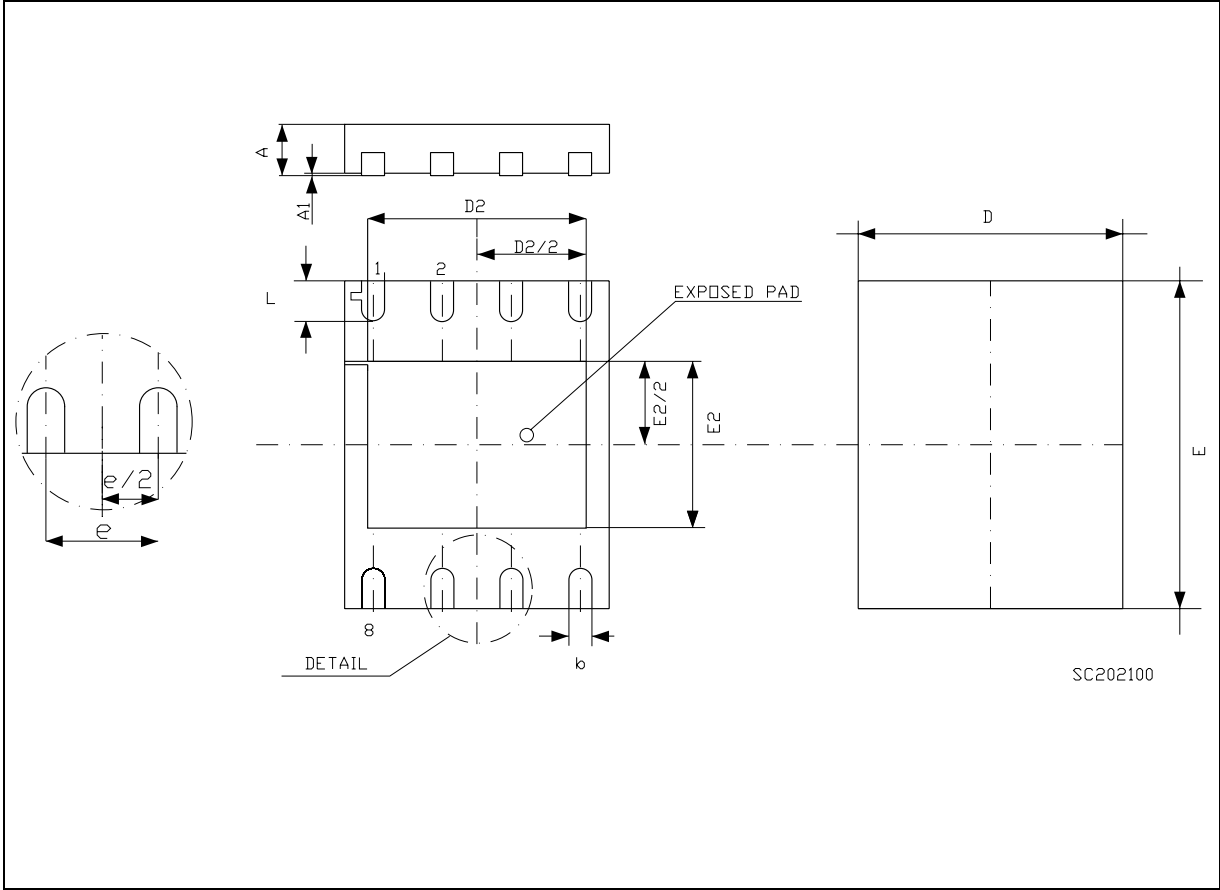


Fig. 3: Test Circuit For Diode Recovery Behaviour



PowerFLAT™(6x5) MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	0.80		1.00	0.031		0.039
A1		0.08			0.003	
b	0.36		0.48	0.014		0.018
D		4.89			0.191	
D2	3.95		4.05	0.154		0.158
E		6.00			0.235	
E2	2.95		3.05	0.115		0.119
e		1.27			0.049	
L	0.65		0.85	0.025		0.033



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